SURFBOARDS[®]

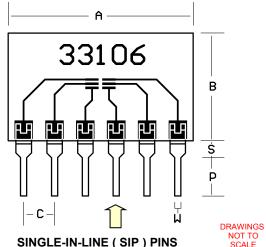


THE BREADBOARDING MEDIUM FOR SURFACE MOUNT TM

33000 SERIES APPLICATION SPECIFIC ADAPTERS IDS33106 REV A- 10-2011

MODEL 33106

6 LEAD .35 mm PITCH DEVICES DEVICE LEAD WIDTH .9, 1.0, To Max 2.2 MM



SINGLE-IN-LINE (SIP) PINS ON .100 in. CENTERS

PAD SET EXAMPLE DEVICE (J) AND MAX WIDTH (1) - D -E-ጉፍ - F |-.T1-|-J-|

MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING. SEE WEBSITE FOR SOLDERING SUGGESTIONS

BOARD SPECIFICATIONS



BOARD MATERIAL: .8mm. +-.13mm .031in+-..005 in. Thick G-10 FR-4 Glass Epoxy or equivalent. CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +- .5mm .020in.

	н	.3	.012	GAP
	I	2.2	.087	MAX LEAD WIDTH
	J	1.0	.039	TYPICAL LEAD WIDTH
	J1	.9	.035	VARIATION LEAD WIDTH
2	Р	3.3	.130	LENGTH FROM SHOULDER +5mm .020in
-	S	1.57	.062	PIN SHOULDER HEGHT

TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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ACCEPTS SOT-963

PARTIAL LISTING

ON SEMI	ULLGA6 1.0x1.0,0.35P
PANASONIC	SSSMini6-F1
TEXAS NST.	DSF (S-PDSO-N6) DSF (S-PX2SON-N6)
TOSHIBA	CST6, FS6

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

Feature Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers. Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

FIG.	мм	IN.	NOTE:
Α	15.24	.600	BOARD WIDTH +5mm .020in.
В	8.89	.350	BOARD HEIGHT +5mm .020in.
С	2.54	.100	SIP PIN SPACE +20mm .008in.
D	1.4	.055	PAD CENTERLINE
Е	.35	.014	DEVICE LEAD PITCH
F	1.1	.043	PAD LENGTH
G	.2	.008	PAD WIDTH
н	.3	.012	GAP
I	2.2	.087	MAX LEAD WIDTH
J	1.0	.039	TYPICAL LEAD WIDTH
J1	.9	.035	VARIATION LEAD WIDTH
Р	3.3	.130	LENGTH FROM SHOULDER +5mm .020in.
S	1.57	.062	PIN SHOULDER HEGHT
W	.5	.020	PIN WIDTH